

High-Speed Bus System Design Challenges

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Agenda

- ◆ Introduction
- ◆ HFSS (High Frequency Modeling, High-order modes)
- ◆ Impacts of High Frequency Modeling on Interconnections
- ◆ Time & Frequency Domain Simulations
 - S-parameters (Return loss and Insertion loss analyses)
 - Tapered line
 - Split Plane
 - Return Path Discontinuities
 - ◆ Chang reference planes
 - ◆ Reference power plane
 - Socket
- ◆ Back up Slides
 - S-parameters
 - RLCG to S-parameters
 - Attenuation (Losses)
 - High Order Mode (TEM & Full wave)
 - Cascading Networks
 - Power Spectrum Density

Introduction

- ◆ High Frequency bit rate about 2.5 to 10 GT/s
 - Mhz → Ghz
 - Lumped element → Partially Distributed → Fully distributed
- ◆ TEM mode
 - Quasi-TEM dominant mode
 - 3D effect (Discontinuity, Split, non-uniformity) not considered
 - Radiation loss not captured
 - Low frequency approximation in extraction
 - No dielectric material (velocity of light $C=300,000$ km/s)
- ◆ High-order mode
 - Group velocity not-equal to phase velocity
 - $C = \text{sqrt}(V_g \cdot V_p)$, { V_g = group velocity & V_p = phase velocity }
 - Non-smooth or non-monotonic S-parameters data
 - Impact on the interconnect model
 - How to improve the performance of interconnect
 - Understanding the impact on timing and noise margins

HFSS

- It is a supplementary tool for understanding in advance the new signal integrity issues such as:
 - Split plane,
 - Reference planes (power \leftrightarrow ground)
 - Return path discontinuity: (changing of reference plane)
 - Impedance mismatches,
 - Resonance peaks
 - Socket and connector effects
- Goal is to optimizing the impact of the different issues on interconnect model

Impacts of High Frequency Modeling on Interconnections

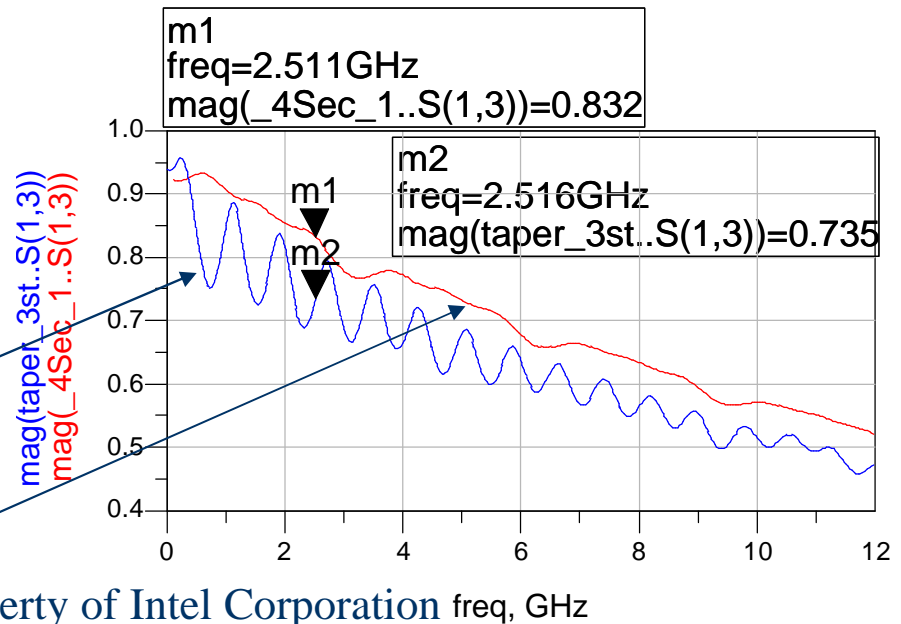
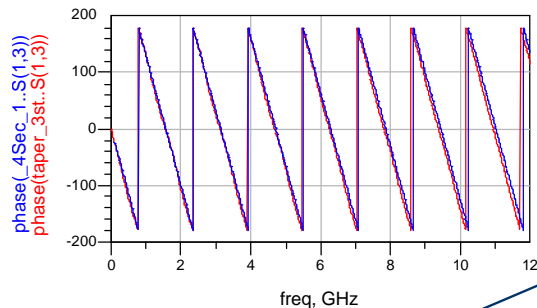
- ◆ Mismatches
- ◆ Delay
- ◆ Stored energy, Reactive Components, (E field and/or H field)
- ◆ Resonance peaks
- ◆ Unstable responses (Time domain issues)
- ◆ Non-passive (frequency domain)

Time & Frequency Domain Simulations

- ◆ Time domain parameters (transient simulation)
 - T_{co}, T_{hld}, T_{su}, Jitter & Skew, Characteristic impedance, Cross-talk
- ◆ Frequency domain parameters (frequency domain simulation)
 - Near and far end cross-talks
 - Return losses
 - Insertion losses

Tapered Line

- ◆ 1.1 dB difference between the two solutions at a particular frequency point (Magnitude)
- ◆ No phase disparity up to 8 GHz



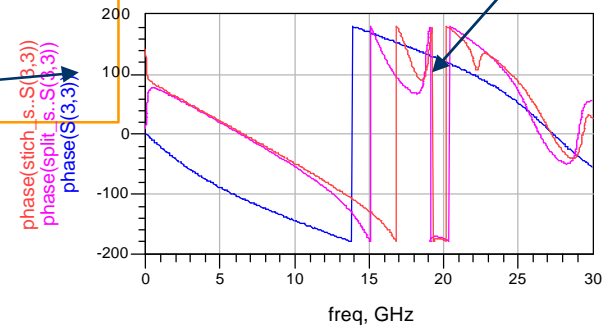
HFSS versus ADS

property of Intel Corporation freq, GHz

Split Plane

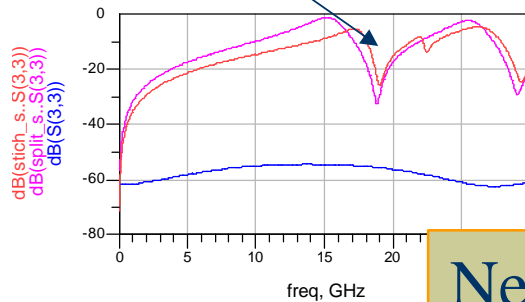
- ◆ Short line over split plane
 - Blue; no-split plane
 - Purple; split plane
 - Red; Stitching planes

Phase Distortions

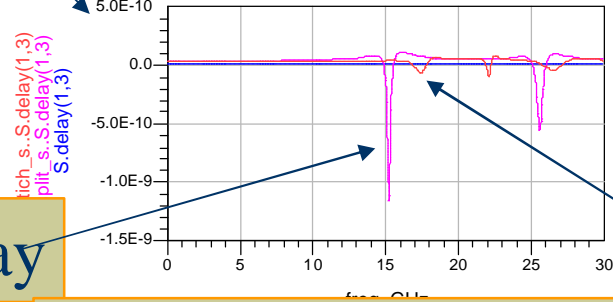


HFSS Sims.

Stored Energy



Negative Delay



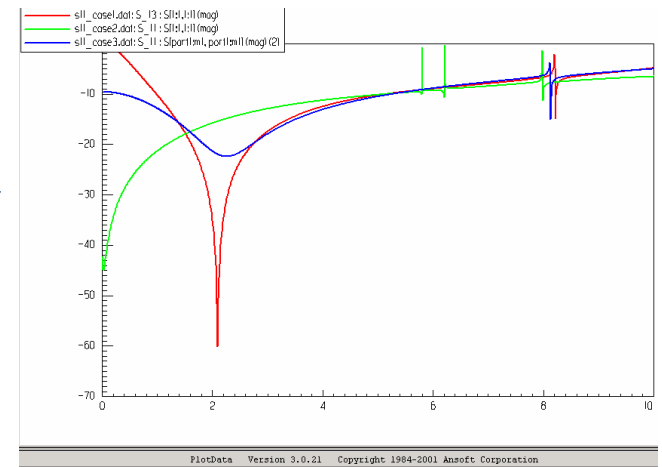
Discontinuities

◆ Reference power plane

- Notch filtering response at 2.1 GHz(energy is trapped)
- De-grade the time domain responses
- Different way of improving such as stitching the two ground planes
- Number of stitching
- Signal integrity issues are serious

Blue; improved by lumped cap
 Red; reference to power
 Green; Short-circuited

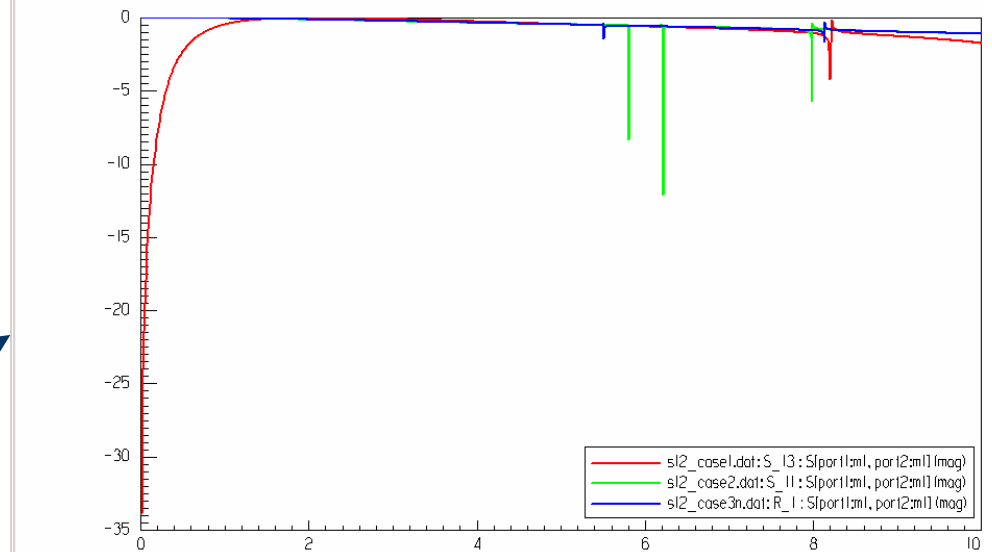
HFSS Sim.



Discontinuities

- ◆ Reference power plane
 - Not much effect on S₁₂
 - Relatively short-line

HFSS Sim.



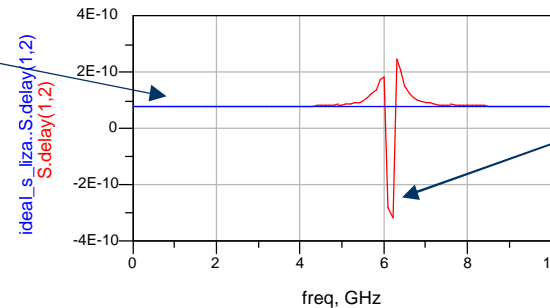
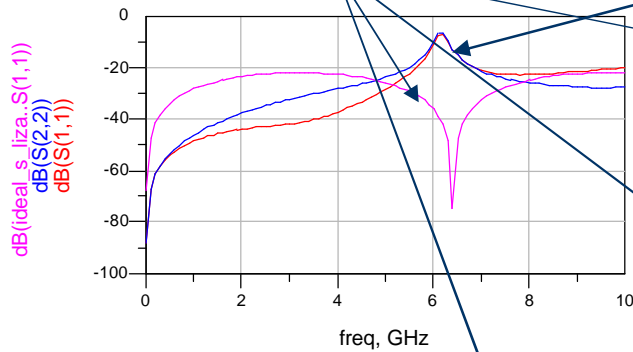
Material is prop

Discontinuities

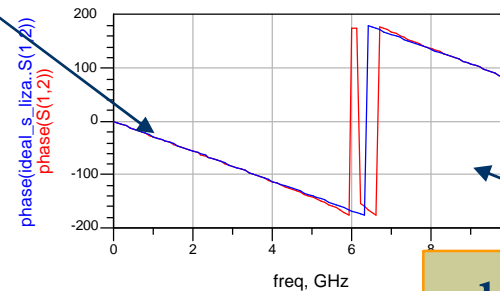
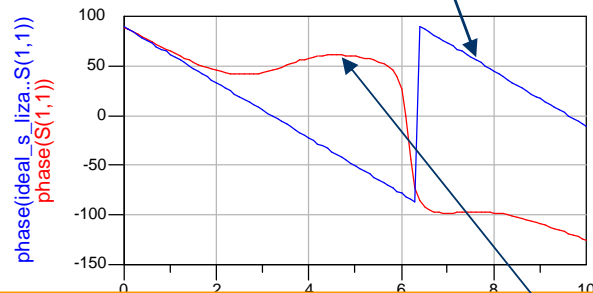
- ◆ Change reference planes

HFSS & ADS Sims.

Stored energy
(Reactive Component)



Negative Delay



phase velocity
Creates delay

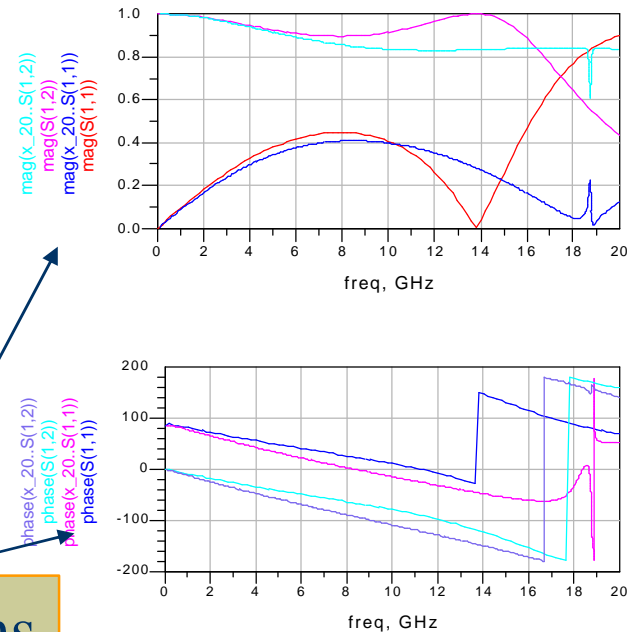
Phase distortion (Non-monotonic phase)

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Socket

- ◆ Lumped spice model is not adequate solution
- ◆ High frequency responses truncated
- ◆ Phase changes add skew
- ◆ Impedance mismatch is an issue

HFSS & ADS Sims

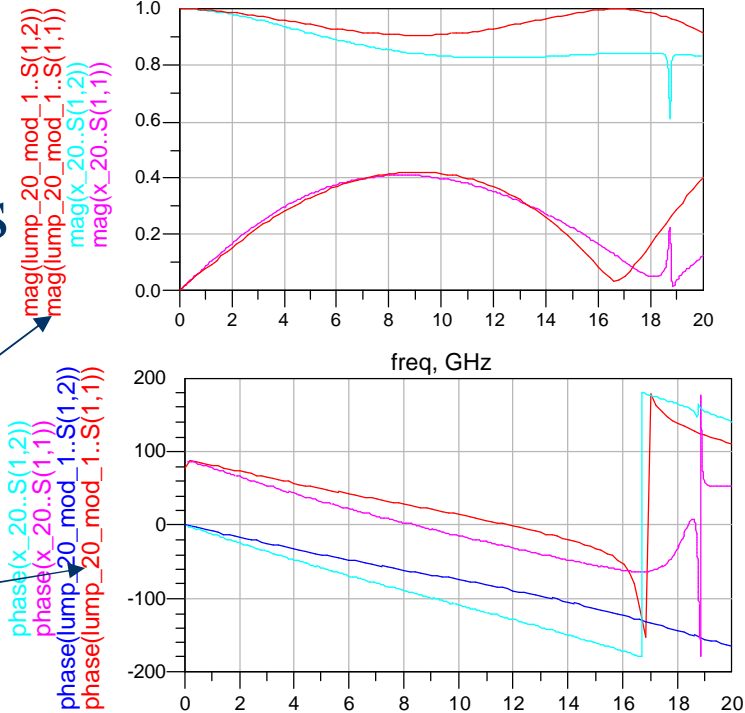


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Socket

- ◆ High frequency solution comprehends all frequencies of interest
- ◆ Better phase response
- ◆ Low-order model works

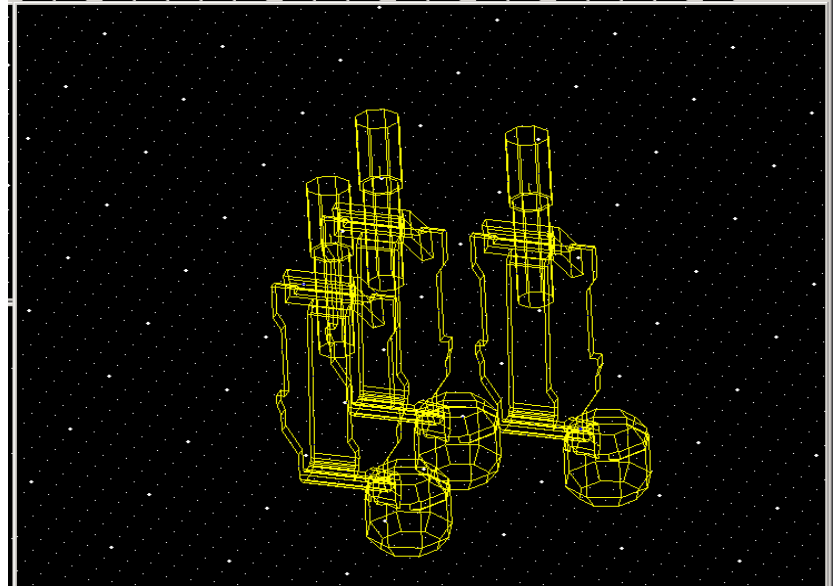
HFSS & ADS Sims



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Socket

- ◆ Two signal lines and one Ground
- ◆ Applying De-embedding method to extract S-parameters
- ◆ Simulate by HFSS



Conclusions

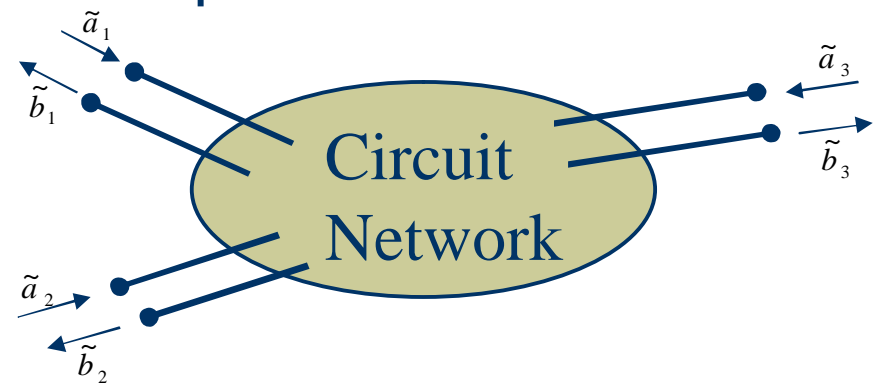
- ◆ In design of high-speed bus, the impacts of high frequency effects are substantial and must be modeled
- ◆ Time and frequency domain simulations are required
- ◆ Need high frequency modeling tool to understand the impact in advance for resolving non-physical behaviors
- ◆ HFSS has been used successfully (S-parameters data)
 - HFSS is not recommended for complete board modeling (very large data base and long simulation times)
- ◆ Design tools must evolve to identify high frequency specific failure mechanisms and permit the designer to avoid them

S-parameters

- ◆ 3D Full wave Solution
- Full-wave (S-parameter) extraction:
 - requires no low frequency assumptions or geometry assumptions
 - solves fully coupled Maxwell's equations

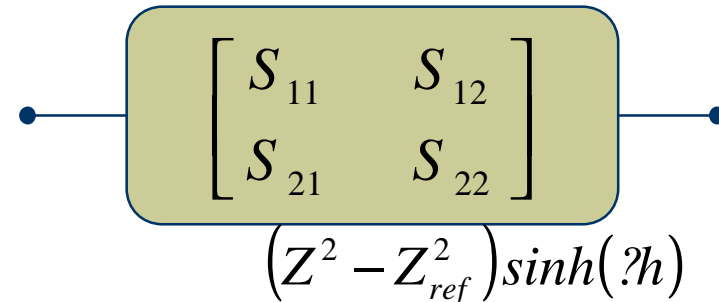
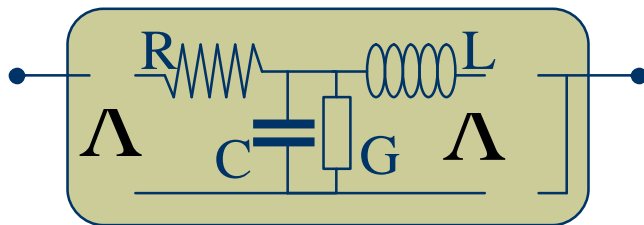
$$[b] = [S][a]$$

- Definition of S-parameters



RLCG to S-parameters

- ◆ RLCG to S-parameters



$$g = \sqrt{(R + j\omega L)(G + j\omega C)}$$

$$Z = \sqrt{\frac{R + j\omega L}{G + j\omega C}}$$

$$S_{11} = S_{22} = \frac{(Z^2 - Z_{ref}^2) \sinh(\gamma h)}{2ZZ_{ref} \cosh(\gamma h) + (Z^2 + Z_{ref}^2) \sinh(\gamma h)}$$

$$S_{12} = S_{21} = \frac{2ZZ_{ref}}{2ZZ_{ref} \cosh(\gamma h) + (Z^2 + Z_{ref}^2) \sinh(\gamma h)}$$

$$Z_{ref} = 50\Omega$$

RLCG not uniquely defined in general

Breakdown regime can be identified from frequency-domain results

S-parameters magnitude are finitely bounded within [-1, 1]

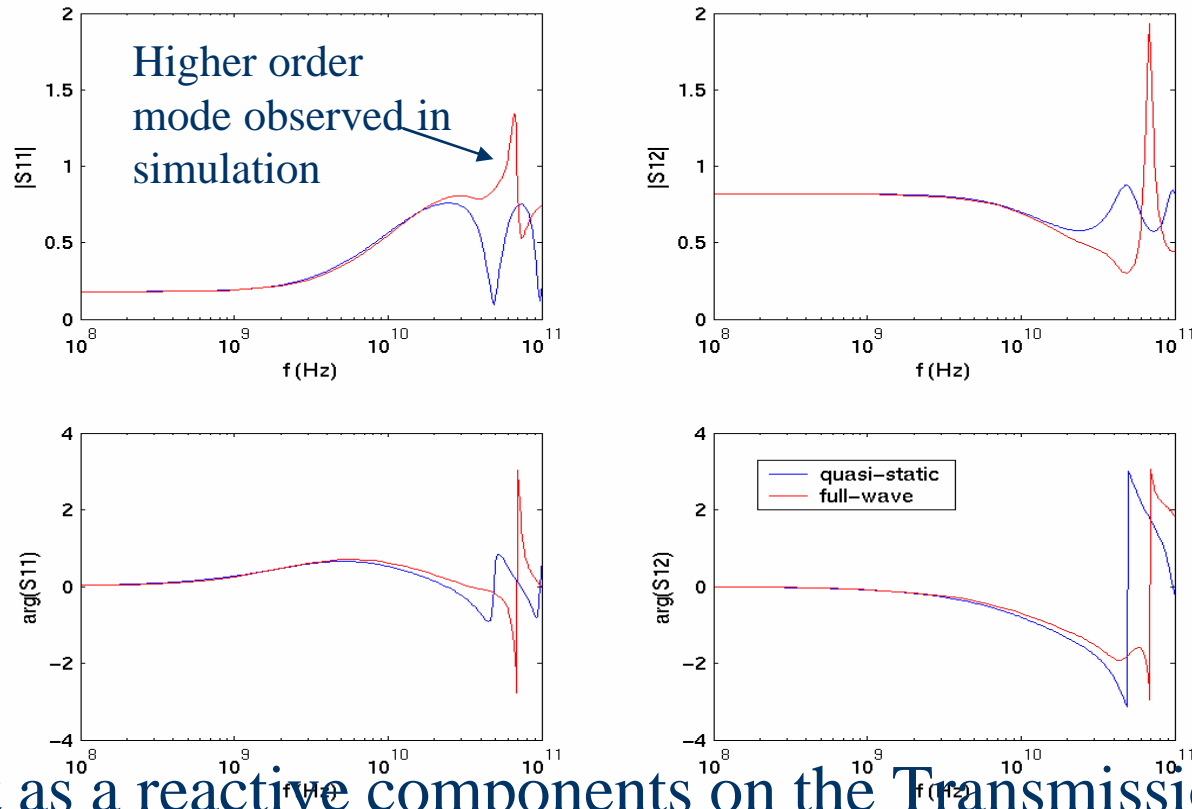
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Attenuation (losses)

- ◆ Conductor losses (Skin Effect)
 - Dissipate energy
- ◆ Dielectric losses (depends on material)
 - Dissipate energy
- ◆ Mismatch losses (If dis. appears in the line or terminations)
 - More serious at high frequency than low frequency
 - Reflect and guide energy away from T.L.
- ◆ Radiation losses

High Order Mode (TEM & FULL Wave)

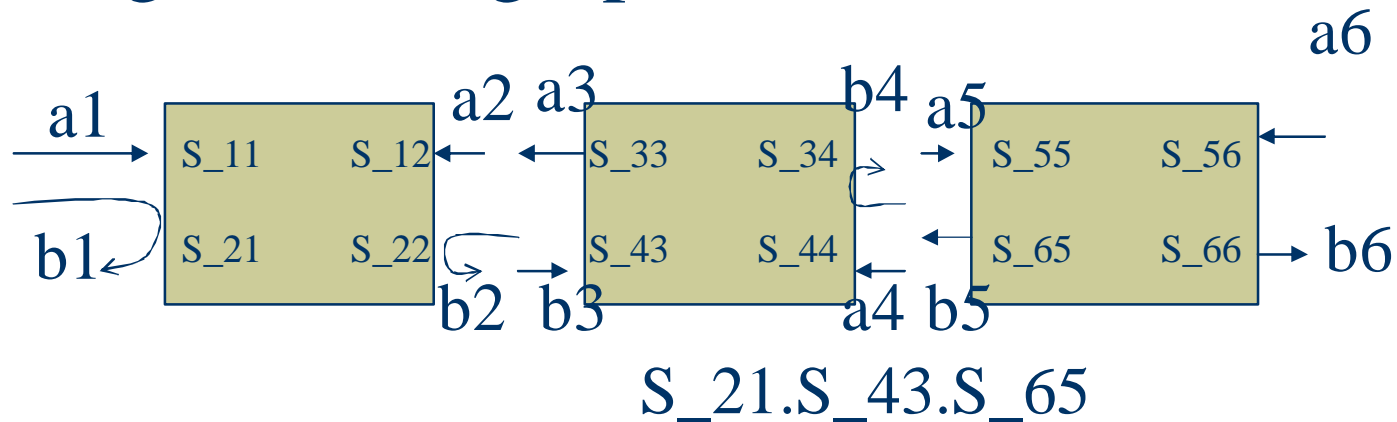
- ◆ S-parameters data TEM Model versus Full wave



Dis. act as a reactive components on the Transmission lines

Cascading Networks

◆ Signal flow graph



$$b6/a1 = \frac{S_{21} \cdot S_{43} \cdot S_{65}}{1 - (S_{22} \cdot S_{23} + S_{44} \cdot S_{55} + S_{43} \cdot S_{55} \cdot S_{34} \cdot S_{22} + S_{22} \cdot S_{33} \cdot S_{44} \cdot S_{55})}$$

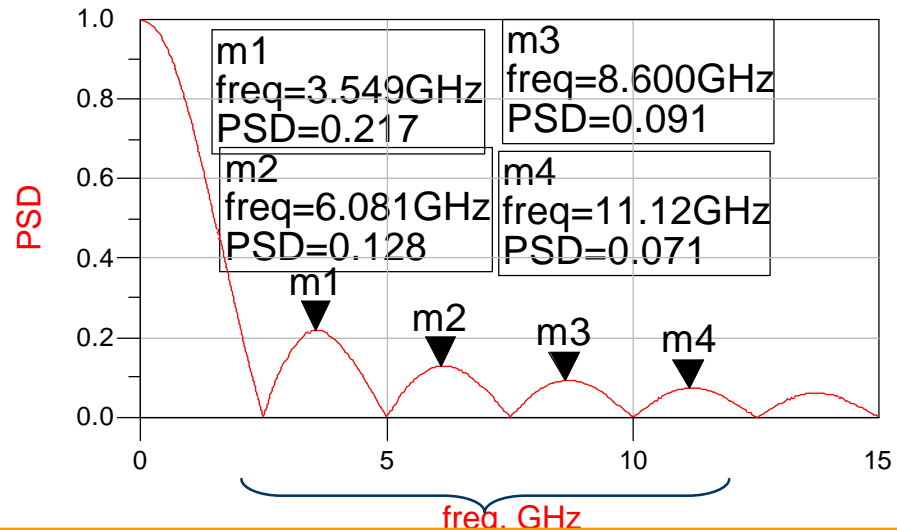
Depends on responses it could be simply add magnitude and phase

Power Spectrum Density

◆ For 2.5 GHz fundamental frequency

- Up to fourth harmonic
- Frequency response up to 11.12 GHz
- Safe for no filtering effects

Eqn $PSD = \text{abs}(\sin(\pi \cdot \text{freq} \cdot 4.e-10)) / (\pi \cdot \text{freq} \cdot 4.e-10)$



Power band width (for not having serious attenuations)